



COMPANY:

ADDRESS:

REQUISITIONER: Mrs. / Mr.

Dep.:

Fax:

Tel:

BUYER: Mrs. / Mr.

Fax:

Tel:

BUILDING INFORMATION

Epoxy Card Metal Blade Card Ceramic Blade Card

This is a

New Order with Device ID: _____
 Re-Order of Device ID: _____
 Change Order of Device ID: _____ in ID: _____

Old Documents of Device ID: _____ to send back to destroy

Number of Probe Cards: _____ Order Number: _____

Number of Probes: _____

Edge Sensor: Qty / Card: _____ non isolated isolated 3-wire

P.C. Board Model: _____

Probing Temperature: Standard = up to 85°C up to 150°C other _____
Probe Material: Standard = Tungsten Be-Cu* Palladium*
Tip Diameter: Standard = 1.5 mils 2 mils 2.5 mils other _____
Tip Length: Standard = 12 mils 7 mils other _____
Tip Shape: Standard = Radiused Flat
Planarity: Standard = 1 mil 0.7 mil* 0.5 mil* 0.3 mil*
Contact Force: Standard = 3 gr./mil Overdrive other
Wafer Size: 4" 5" 6" 8"
Height of Probe Card: 144 mils 154 mils other
Smallest Pad Size: _____ mils x _____ mils _____ µm x _____ µm
Pad Distance: _____ mils
(middle of Pad to middle of Pad)

REQUIRED MATERIAL

In order to build your Probe Card, we need the following:

Wafer, Glasmask* or Film* in the Original Scale. Is there more than one Device on the Wafer?

Yes No If yes, please provide Pad Layout with the Device to use.

Diagram or Sketch showing Pad Positions and a Mark on the Pads to be probed.

Position of the Waferflat in Relation to the Connector of the Probe Card.

Position of the Edge Sensor.

Wiring Diagram / Translation Wiring Diagram / Translation provided No Wiring required

REMARKS:

Requested Delivery Date:

Date: 2010

*extra charge